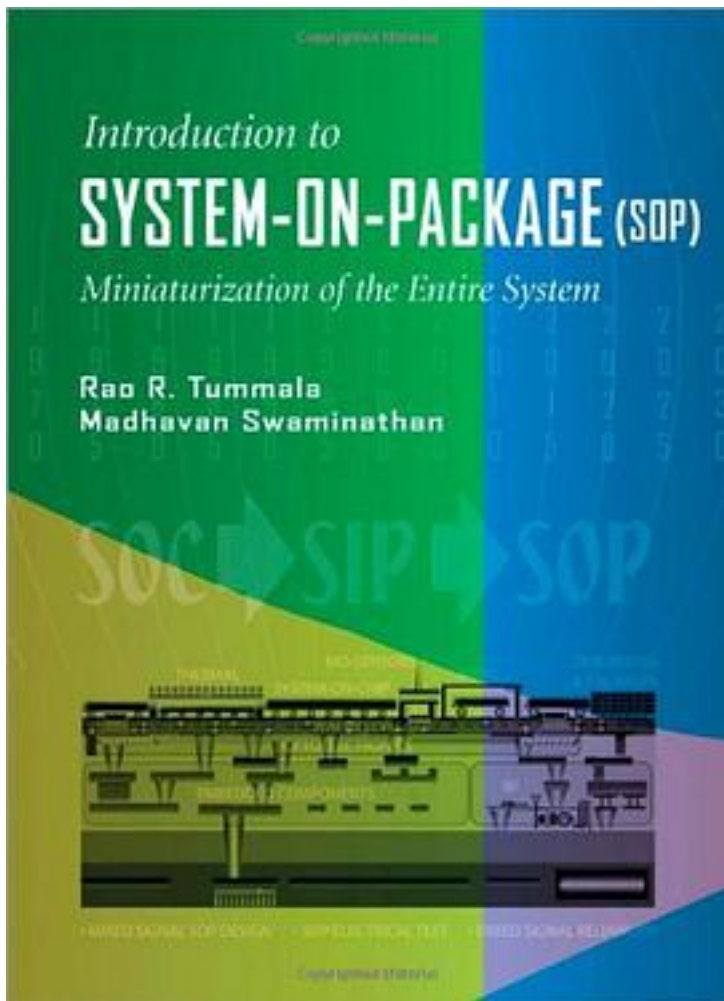


System on Package



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"System-on-Package" (SOP) is an emerging microelectronic technology that places an entire system on a single chip-size package. Where "systems" used to be bulky boxes

housing hundreds of components, SOP saves interconnection time and heat generation by keep a full system with computing, communications, and consumer functions all in a single chip. Written by the Georgia Tech developers of the technology, this book explains the basic parameters, design functions, and manufacturing issues, showing electronic designers how this radical new packaging technology can be used to solve pressing electronics design challenges.

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